



2016 IEEE International Symposium on Radio-Frequency Integration Technology ([RFIT2016](#)) August 24-26, 2016 Taipei, Taiwan

Final Call for Paper (Deadline extended!)

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The 2016 IEEE International Symposium on Radio-Frequency Integration Technology (RFIT2016) will be held at the Howard International House, Taipei, Taiwan, on August 24-26, 2016. This conference is organized and sponsored by the IEEE MTT-S, and will be supported by IEEE MTT-S Taipei Chapter. The European Microwave Association (EuMA) and the Taiwan Electromagnetic Industry-Academia Consortium (TEMIAC) are Technical Co-Sponsors of RFIT2016.

The topics include, but are not limited to, the following technical areas:

1. High-number Spec ICs: high speed/high frequency/high bandwidth/high integration/high performance circuits and systems.
2. Low-number Spec ICs: low power/low voltage/low noise/low complexity circuits and systems.
3. Device Technologies: CMOS, SOI, SiGe, GaAs, LDMOS, GaN, reliability, characterization, CAD, modeling, EM simulation, co-simulation, etc.
4. Packaging technology: MCM, SiP, TSV, MEMS, flip chip assembly, wire bonding, anisotropic conductive film, etc.
5. Passive Circuits and Antenna: on-chip antenna, integrated passive devices, ferrite, piezoelectric material, etc.
6. Frequency Generation ICs: VCOs, PLLs, synthesizers, ADPLL, frequency dividers, multipliers, etc.
7. Building Block RFICs: LNA, PA, mixers, RF front-end, Si-based MMIC, etc.
8. Analog and Mixed Signal ICs: amplifiers, ADC, DAC, comparators, filters, AGC/VGA, etc.
9. RF Sensor ICs: automotive radar, security, wearable devices, biomedical and healthcare applications, etc.
10. Power Transmission: RFIDs, electric coupling, electromagnetic induction, magnetic resonance, wireless power transmission, etc.
11. Emerging ICs: power management, digital RF circuits/architectures, RF BIST, data converters, reconfigurable and tunable ICs, new energy vehicle electronics EM and ICs, etc.

Paper Submission

To encourage timely reporting of the latest results and have better opportunities to expand papers for possible journal publications, prospective authors are invited to submit a **3-page** manuscript (both initial submission and final manuscript, if accepted) in English and in IEEE PDF eXpress format. The manuscript should emphasize original contributions and key findings, including figures, diagrams and results from both simulations and measurements. References should be clearly cited and up-to-date. If accepted, the manuscript will be published in IEEE Xplore. By submitting a manuscript, the authors promise that, if accepted, at least one of them will attend RFIT2016 with full registration.

The deadline for technical paper submissions is extended to 15 April, 2016.

Manuscript submission deadline: ~~1 April 2016~~ **15 April 2016**

Notification of Acceptance: **13 May 2016**

Submission of final manuscript: **10 June 2016**

All must be made through the RFIT2016 portal: www.rfit2016.org



About RFIT

RFIT is a focused yet interdisciplinary advanced forum for microwave and microelectronics technologies. RFIT is an annual event in region 10 solely sponsored by IEEE MTT Society. It will rotate among Taiwan, Korea, Singapore, China, and Japan, and will be held in end of August or beginning of September every year.

RFIT provides a forum for the integrated circuit and technology communities to meet and present the latest developments in integrated circuit design, technology and system integration, with emphasis on wireless communication systems and emerging applications such as biology and healthcare, as well as emerging THz and 3D integration technologies.

RFIT will continue to feature both invited and contributed papers. Distinguished researchers will be invited to deliver keynote speeches and invited talks on technology trends and significant advances. The best papers will be selected from the contributed papers for awards. Both invited and contributed papers that are accepted by RFIT will appear in the IEEE Xplore, Science Citation Index (SCI) and Engineering Index (EI). Extended versions of the papers can be submitted to the IEEE Transactions on Microwave Theory and Techniques.

Author Registration and Paper Submission Steps:

1. Author registration form: title, author(s) and affiliation(s), and statement of exclusivity. This form also includes a 30-50 word abstract (description of the subject, its importance, and how the work contributes to the field). This information is required and must be submitted via the conference website: www.rfit2016.org.
2. Authors must use the template provided on the website to format their manuscript. **The manuscript may not exceed 3 pages total and the file size must be less than 2 MB. For PDF files, use Distiller and select "embed all fonts". Please note that we are not accepting *.doc files.**
3. Submission deadline: ~~4 April 2016~~ **15 April 2016**
Submissions will be acknowledged instantly.
HARD copy and FAX submissions will NOT be accepted.
Late submissions will NOT be considered.
Authors of accepted papers will be required to submit a detailed paper, along with a clear die or prototype photo of the work described in the manuscript.

Student Paper Competition

A Student Paper Competition will be held as part of the Symposium. Student papers will be reviewed in the same manner as all other papers. Papers accepted for the competition will be judged on content and presentations (poster and oral). To be considered for an award, the student must have been a full-time student during the time the work was performed, be the lead author, and must present the paper at the Symposium.

Student Design Competition

The RFIT student design competition is open to all students, both undergraduate and graduate, registered at a recognized educational establishment. The winner is determined by the measurement results in the competition.

Taipei City



Access to Taipei

- **Taoyuan International Airport:**
Take the high-speed rail (HSR) to Taipei Railway Station and transfer to Taipei MRT or taxi.
- **Songshan Airport:**
Take a taxi for about 20 minutes.

Venue

Howard International House
(福華文教會館)

Website: <http://intl-house.howard-hotels.com/>

Address: No. 30, Sec. 3, Xinsheng S. Rd.,
Da'an Dist., Taipei City 106, Taiwan.